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Test Beam study of small-pitch 3D pixel sensors from CNM

Silicon pixel sensors of cell size 50 μm x 50 μm fabricated at CNM using 3D, doubled-sided n-on-p technology were bump-bonded to ROC4Sens readout chips and tested in an electron test beam at DESY. We show initial results of efficiency, charge collection, charge sharing, noise and resolution for different track incidence angles. The sensor+ROC assemblies were later irradiated with protons to a fluence of 3e15 neq/cm². Preliminary results of irradiated sensors are also shown.

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